

ASEK764, Demo Board, Socket

85-0554-001-FAB  
Originator: S. Upton

## FAB Drawing

Rev 1  
10/4/2012

1. Finished PCB is RoHS
2. Laminate: FR4, 0.062 inch thick
3. Mill PCB edge according to Mech 1 layer (\*.g1)
4. Layer count: 2
5. Finished copper thickness: 2oz outer
6. Via barrel plating: plate to 1mil thick minimum
7. Min Trace Width = 10mil, Min Trace Separation = 8mil
8. Min Silkscreen Width: 8mil
9. Finish: immersion gold
10. Top/bottom soldermask. Color = Green
11. Top silkscreen. Color = White
12. No Blind or Buried Vias
13. Hole sizes specified are after plating
14. Contact Information  
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Layer Stack Up Detail for: 85-0554-001 R1.PCBD0C

Layer Name	Gerber Document	Copper Thickness
Top Solder Mask	(.GTS)	
TopLayer	(.GTL)	2.8mil
BottomLayer	(.GBL)	2.8mil
Bottom Solder Mask	(.GBS)	

Mechanical Layer 1 \*.gm1 is Board Outline, slots and circular cutouts  
Mechanical Layer 2 \*.gm2 is footprint notes (not for fab house)  
Mechanical Layer 3 \*.gm3 is hole location guide  
Mechanical Layer 4 \*.gm4 is board outline dimensions  
Mechanical Layer 5 \*.gm5 is topside labels (if no silk)  
Mechanical Layer 6 \*.gm6 is bottomside labels (if no silk)

Symbol	Hit Count	Tool Size	Plated	Hole Type
□	127	15mil (0.381mm)	PTH	Round
○	24	31.496mil (0.8mm)	PTH	Round
☆	20	35.433mil (0.9mm)	PTH	Round
▽	29	42mil (1.067mm)	PTH	Round
⊕	2	56mil (1.422mm)	PTH	Round
⊗	2	59.055mil (1.5mm)	PTH	Round
⊗	10	62mil (1.575mm)	PTH	Round
□	4	125mil (3.175mm)	PTH	Round
◇	4	266mil (6.756mm)	PTH	Round
	222 Total			





